

Appl. No. 10/774,783
Art Unit: 1751

IN THE ABSTRACT:

Please replace the current abstract with the new abstract attached herewith on a separate sheet.

CLEANING AGENT INCLUDING A CORROSION INHIBITOR USED IN A PROCESS OF FORMING A SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

A cleaning solution is provided. The cleaning solution includes deionized water, a surfactant and a corrosion inhibitor comprising a triple bond and at least one hydroxyl group. The surfactant in the cleaning solution is $C_{12}H_{25}O(CH_2CH_2O)_JH$ and wherein J is an integer ranging from 5 to 15. The cleaning solution may further include an acid solution or an alkaline solution. Also, the surfactant may be included, for example, in an amount of about 0.0001 to about 10wt.% of the cleaning solution.